



## 6-layer PCB stackup



### Parameters

|   |                               |
|---|-------------------------------|
| material type:                                  | Standard FR4 TG130            |
| base materials thickness (after lamination):    | 2.001 mm                      |
| final PCB thickness:                            | 2.17 mm ±0.13 mm              |
| Cu thickness:                                   |                               |
| outer layers (base thickness, without plating): | 18 µm                         |
| inner layers (final thickness):                 | 35 µm / 35 µm / 35 µm / 35 µm |